



Printed Circuit Boards
Interconnection Carriers

PRINTED CIRCUIT BOARDS

01

31.10.2013

1/1

Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
---	---	---	---	---	---	-----------

04 121 FR4 35 L71.35 P18

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_121_FR4_35_L71.35_p18

Layers	in μ	Material	Build-Up	Assembly
Layer-1	35 μ	Copper		A1
	180 μ	Prepreg		
Layer-2	35 μ	Copper		B
	710 μ	L-FR4		
Layer-3	35 μ	Copper		
	180 μ	Prepreg		
Layer-99	35 μ	Copper		

© Copyright by Printed Circuit Boards GmbH